

**Addition of Abstract**

Please add the following Abstract to the application. This Abstract being summarized from the Abstract on the published PCT application (WO 2005/015632).

**ABSTRACT OF THE DISCLOSURE**

A multichip circuit module includes a main board, at least one carrier substrate mounted on and in electrical contact with the main board, and at least one semiconductor chip arranged on the carrier substrate and in electrical contact therewith. The carrier substrate has at least one cavity on an assembly surface for receiving the semiconductor chip. The cavity includes connecting contacts which join with associated bumps on the semiconductor chip using a flip-chip technique. The assembly surface of the carrier substrate is placed on a contact surface of the main board, and a filling material is provided between the contract surface of the main board and the assembly surface of the carrier substrate.